

PRODUCT NO.
73725

PRODUCT NUMBER CODE

73725-X X X X LF

HOUSING COLOR OPTION
0-WHITE
1-BLACK

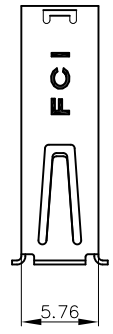
SENSOR CONTACT OPTION
0-WITH SENSOR CONTACT
1-WITHOUT SENSOR CONTACT

SHIELD PLATING OPTION
1- 1.25μm MINIMUM NICKEL UNDERPLATE &
2.5μm MINIMUM BRIGHT TIN OVER ALL AREA.
(HOLD DOWN STYLE "A")
2- 1.25μm MINIMUM NICKEL UNDERPLATED OVER ALL;
2.5 μm MINIMUM MATTE TIN PLATED ON
HOLD DOWN AREA ONLY.(HOLD DOWN STYLE "B")
3- 1.25μm MINIMUM NICKEL UNDERPLATED OVER ALL;
2.5 μm MINIMUM MATTE TIN PLATED ON
HOLD DOWN AREA ONLY.(HOLD DOWN STYLE "A")
4- 1.25μm MINIMUM NICKEL UNDERPLATED &
2.5μm MINIMUM BRIGHT TIN OVER ALL AREA.
(HOLD DOWN STYLE "B")
5- 1.25μm MINIMUM NICKEL UNDERPLATED OVER ALL;
2.5μm MINIMUM MATTE TIN PLATED ON
HOLD DOWN AREA ONLY (HOLD DOWN STYLE "C")
6- 1.25μm MINIMUM NICKEL ONLY.
(HOLD DOWN STYLE "A")
7- 1.25μm MINIMUM NICKEL UNDERPLATED &
2.5 μm MINIMUM MATTE TIN PLATED OVER ALL.
(HOLD DOWN STYLE "A")
8- 1.25μm MINIMUM NICKEL UNDERPLATED &
2.5 μm MINIMUM MATTE TIN PLATED ALL AREA.
(HOLD DOWN STYLE "B")
9- 1.25μm MINIMUM NICKEL UNDERPLATED OVER ALL;
2.5 μm MINIMUM MATTE TIN PLATED ON
HOLD DOWN AREA ONLY (HOLD DOWN STYLE "D")
S- 1.25μm MINIMUM NICKEL ONLY.(HOLD DOWN STYLE "A").
HIGH PERFORMANCE MATERIAL
FOR 12,000 DURABILITY CYCLES
A- 1.25μm MINIMUM NICKEL PLATED OVER ALL
2.5 μm MINIMUM MATTE TIN PLATED ON HOLD DOWN AREA ONLY
(HOLD DOWN STYLE "F")
B- 1.25μm MINIMUM NICKEL PLATED OVER ALL
2.5 μm MINIMUM MATTE TIN PLATED ON HOLD DOWN AREA ONLY
(HOLD DOWN STYLE "F")

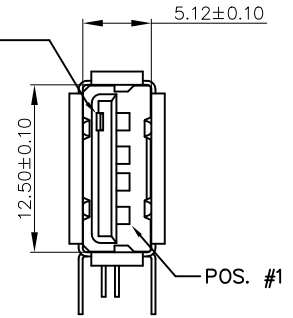
TERMINAL OPTION
50u" NI UNDERPLATE; 30u" GXT CONTACT AREA,100u" TIN TAIL AREA;
0- DIM "A": 2.29 (TERMINAL TAIL LENGTH);
1- DIM "A": 3.71 (TERMINAL TAIL LENGTH);

LEAD FREE OPTION
SEE NOTE 9

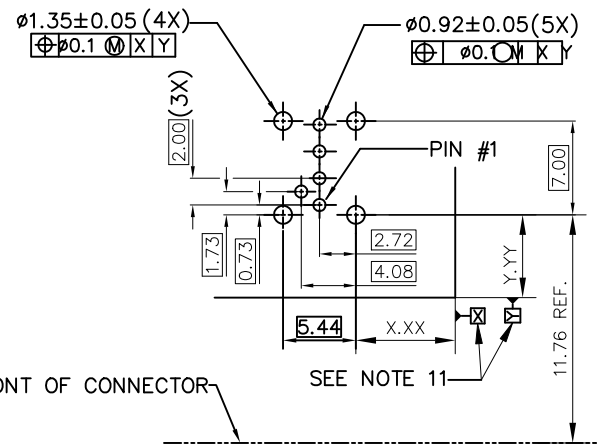
PACKAGING OPTION
B - TUBE
R - TAPE&REEL



SENSOR CONTACT

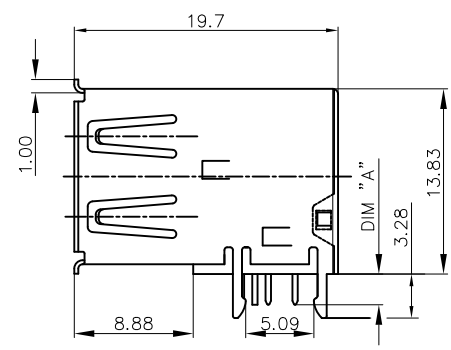


WITH SENSOR CONTACT



FRONT OF CONNECTOR

PC BOARD MOUNTING DIMENSIONS FOR 5 PIN



FOR 73725-X0X0B
HOLD DOWN STYLE "A"

NOTES:

- MATERIAL:
CONTACTS: COPPER ALLOY
SHIELD: COPPER ALLOY
HOUSING: UL 94V-0 THERMOPLASTIC, COLOR: SEE PRODUCT CODE
- PLATING:
CONTACTS: GOLD FLASH OVER PALLADIUM NICKEL (0.76μm MINIMUM)
IN CONTACT AREA; 2.5 μm TIN MINIMUM IN SOLDER TAIL AREA.
1.27 μm MINIMUM NICKEL UNDERPLATE OVER ALL SURFACES.
SHIELD: SEE PRODUCT NUMBER CODE.
(THE PLATING MEASURE POINT ON THE SHIELD HOLD DOWN AREA ONLY).
- DATUMS & BASIC DIMENSIONS TO BE DETERMINED BY CUSTOMER
- RECOMMENDED PCB BOARD THICKNESS IS 1.00 ~ 1.60mm EXCEPT 73725-1191BLF;
73725-1191BLF CAN BE USED FOR THE PCB BOARD THICKNESS 2.30 ~ 2.65mm.
- MAXIMUM PANEL THICKNESS TO BE 2.67mm IF MOUNTED BEHIND PANEL
- METAL SHELL SLIVER 0.20 MAX.
- NI PLATING DOES NOT COMPLY WITH THE USB STANDARDS
(TO BE CONTINUED)

mat'l. code				surface ¹²³ /tolerance		projection 	product family HPL 511 USB 2.0			
ltr	ecn no	dr	date	ISO 1302	ISO 406 ISO 1101		title			
AJ	ELX-N-27706	LZ	2017/08/15	tolerances unless otherwise specified			USB UP-RIGHT RECEPT			
				angles	linear					
AD	ELX-N-012006	A.ZH	06/25/2012	0°±2'		scale 1:1	dwg no sheet 1 of 4 size 73725 A3			
AE	ELX-N-13463	A.ZH	11/14/2012	dr	PAMP	5/20/97				
AF	ELX-N-14592	J.HAN	06/10/2013	engr	R Y LIU	5/20/97				
AG	ELX-N-21594	LQ	08/04/2015	chr	R Y LIU	5/20/97				
AH	ELX-N-21919	LQ	08/04/2015	appd	JENN TSAO	5/20/97				
sheet index		revision sheet						type Product Customer Drawing		

PRODUCT NO.
73725

(CONTINUED)

8. P/N'S WITH SUFFIX "LF" ARE LEAD FREE P/N'S

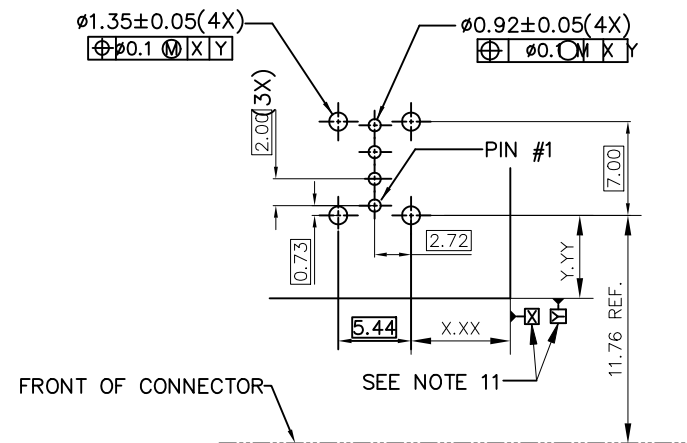
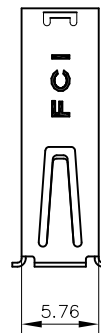
FOR LEAD FREE P/N, THE PRODUCT MEET EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATION AS DESCRIBED IN GS-22-008

FOR THE PRODUCTS WITH THE METAL SHELL PLATING NICKEL AND MATTE SN CAN WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 40 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW PROCESS; FOR THE PRODUCTS WITH METAL SHELL PLATING BRIGHT SN OR SEMI-BRIGHT SN CAN'T WITHSTAND REFLOW AND JUST CAN WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN WAVE SOLDERING PROCESS.

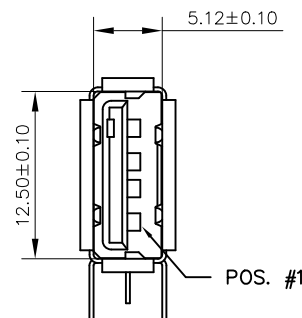
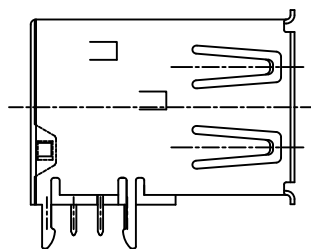
FOR ALL LEAD FREE P/N'S, WITH SUFFIX LF.

12. THE PRODUCT CAN BE USED FOR PIP PROCESS

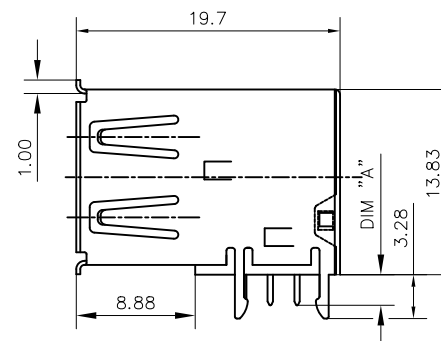
13. DATUM OF CUSTOMER'S PCB LAYOUT.



PC BOARD MOUNTING DIMENSIONS FOR 4 PIN

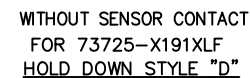
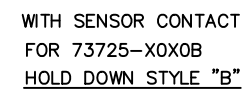
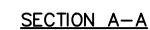
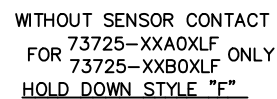
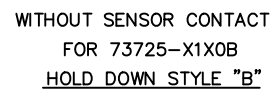


WITHOUT SENSOR CONTACT



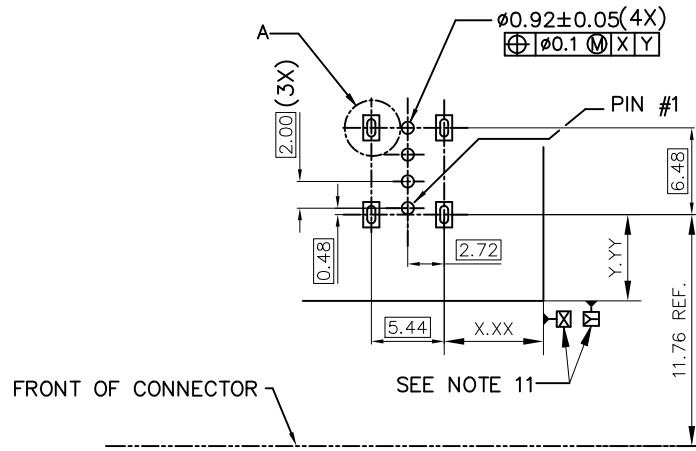
FOR 73725-X1X0B
HOLD DOWN STYLE "A"

mat'l. code				surface ¹²³ /tolerance			projection		product family		
				ISO 1302 ✓ ISO 406 ISO 1101					HPL 511 USB 2.0		
ltr	ecn	no	dr	date			tolerances unless otherwise specified		title		
AJ							mm		USB UP-RIGHT RECEPT		
				angles			.0±.30				
				linear			.00±.20				
				0°±2'			.000±.10				
				dr			PAMP		5/20/97		
				eng			R Y LIU		5/20/97		
				chr			R Y LIU		5/20/97		
				appd			JENN TSAO		5/20/97		
sheet		revision								dwg no	
index		sheet								sheet2 of 4	
										size	
										A3	
										type	
										Product Customer Drawing	

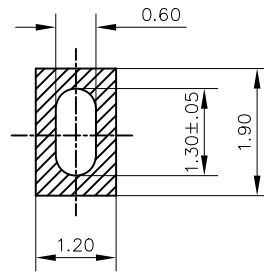


mat'l. code				surface ¹²³ /tolerance ISO 1302 ISO 406 ISO 1101			projection 		product family HPL 511 USB 2.0			
ltr	ecn no	dr	date	tolerances unless otherwise specified					title			
AJ				angles		.0±.30			USB UP-RIGHT RECEPT			
				linear		.00±.20						
				0°±2°		.000±.10	scale 1:1					
				dr	PAMP	5/20/97	Amphenol FCI		dwg no		sheet3 of 4	size
				engr	R Y LIU	5/20/97			73725		A3	
				chr	R Y LIU	5/20/97						
				appd	JENN TSAO	5/20/97						
sheet index		revision sheet							type Product Customer Drawing			

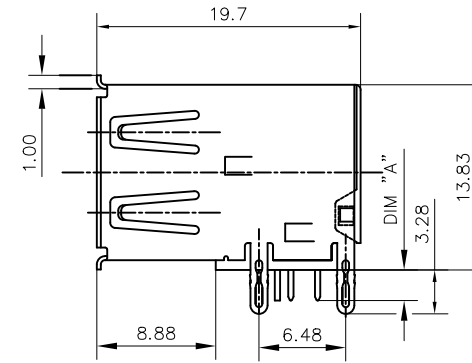
PRODUCT NO.
73725



PC BOARD MOUNTING DIMENSIONS FOR 4 PIN



DETAIL A 5 : 1



WITHOUT SENSOR CONTACT
FOR 73725-X150B
HOLD DOWN STYLE "C"

mat'l. code					surface ₁₂₃ ✓		tolerance		projection		product family												
					ISO 1302		ISO 406 ISO 1101				HPL 511 USB 2.0												
ltr		ecn		no	dr	date		tolerances unless otherwise specified						title									
AJ								angles		linear		.0±.30				mm		USB UP-RIGHT RECEPT					
								0±2°		.00±.20		.000±.10											
												scale 1:1											
								dr		PAMP		5/20/97		Amphenol FCI		dwg no				sheet 4 of 4		size	
								engr		R Y LIU		5/20/97				73725				A3			
								chr		R Y LIU		5/20/97											
								appd		JENN TSAO		5/20/97											
sheet index		revision sheet																					



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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Факс: 8 (812) 320-02-42

Электронная почта: org@eplast1.ru

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